

Update on forward tracking from the Spanish future collider network

Pixel solution for forward region
(IFIC/DEPFET)

Micro-strip detectors with intrinsic gain
(IFCA/CNM-IMB)

FTD thermo-mechanical
(IFCA/IFIC Valencia)



ILD optimization workshop, DESY, February 2016

M. Vos, IFIC (UVEG/CSIC) Valencia



Forward tracking (is)

Important:

Forward tracking at the next e+e- collider.
Part I: the physics case,
JINST 4 (2009) P08002

Many processes are forward-peaked at $\sqrt{s} \gg m_Z$

- Higgs boson through VBF
- Di-boson production
- Any t-channel with a light mediator
- Bread-and-butter $e^+e^- \rightarrow f\bar{f} (\gamma)$

Challenging:

Forward tracking at the next e+e- collider.
Part II: experimental challenges and detector design,
JINST 8 (2013) T06001

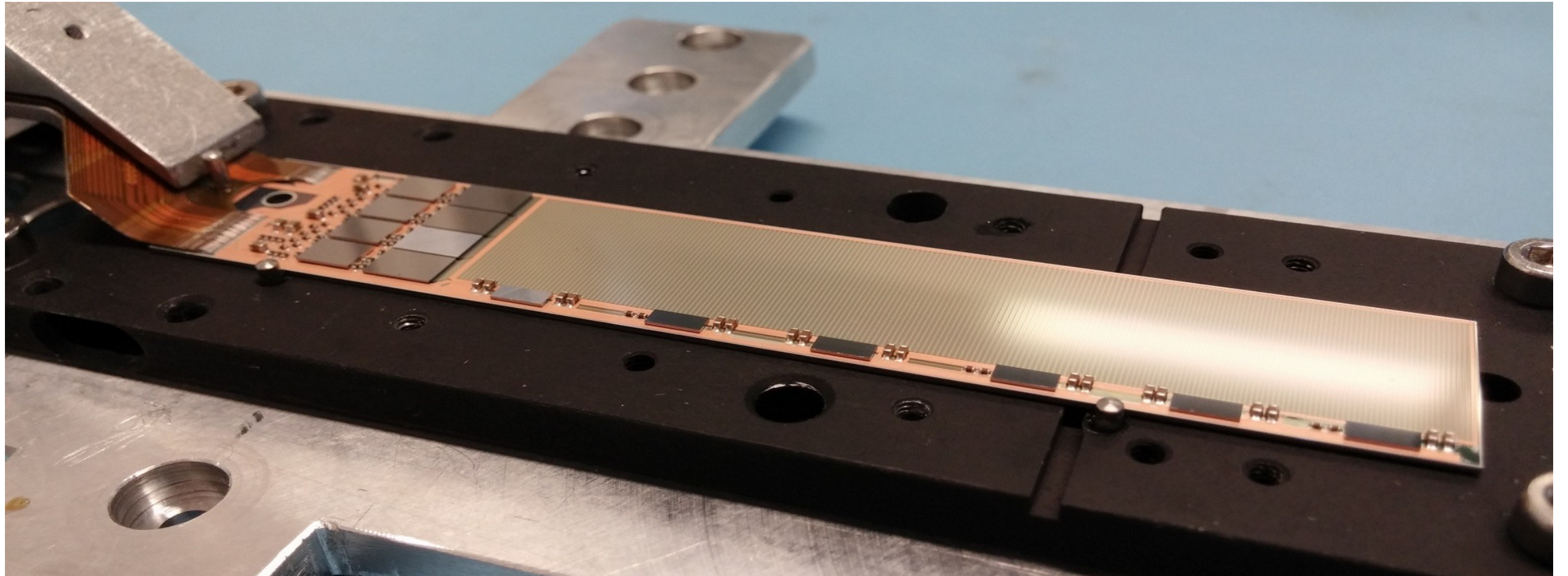
Hard to keep good performance vs. polar angle

- backgrounds ($\gamma\gamma \rightarrow$ hadrons)
- pattern recognition, low p_T tracks
(see previous talk)
- p_T resolution \rightarrow orientation magnetic field
- vertexing \rightarrow distance + material



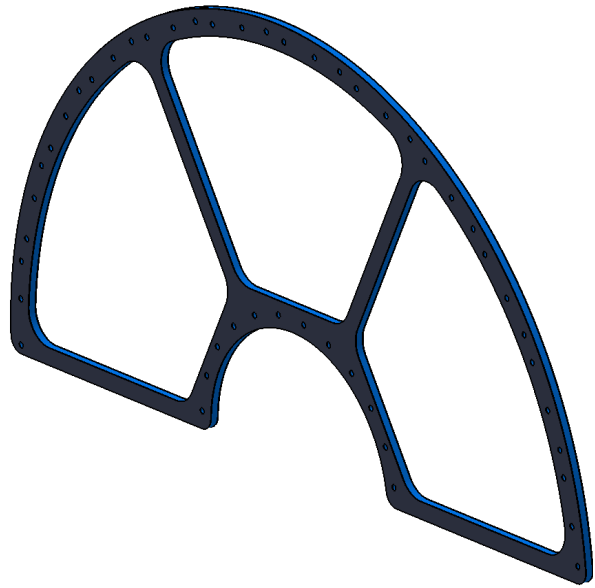
Final DEPFET half-ladder

Fully functional.... major milestone for the Belle II project!



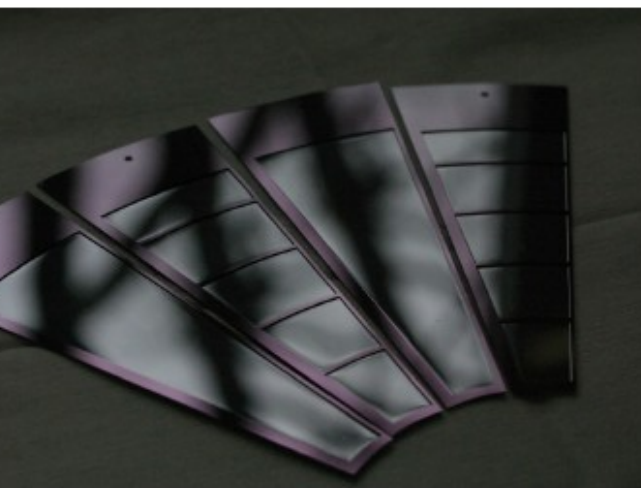
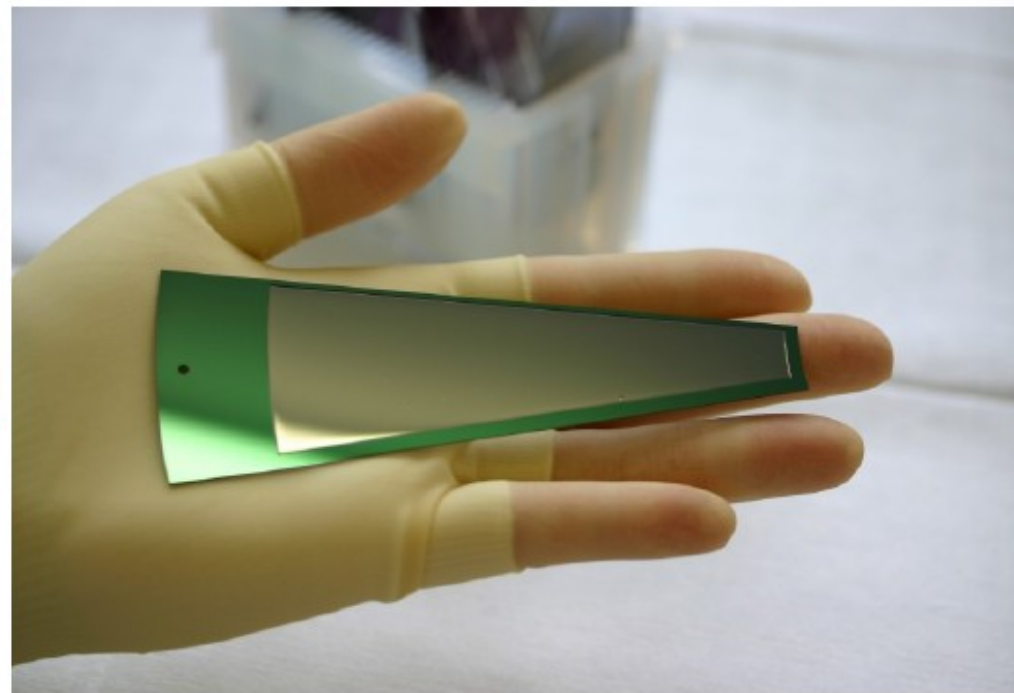
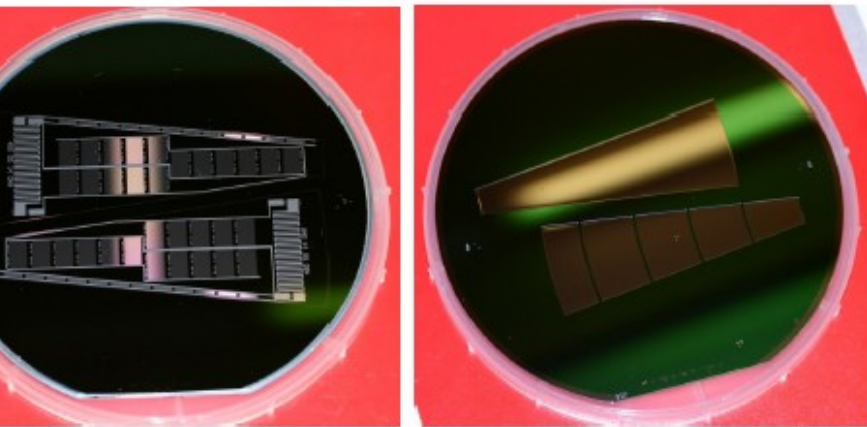
And it works... detailed electrical characterization + TB ongoing





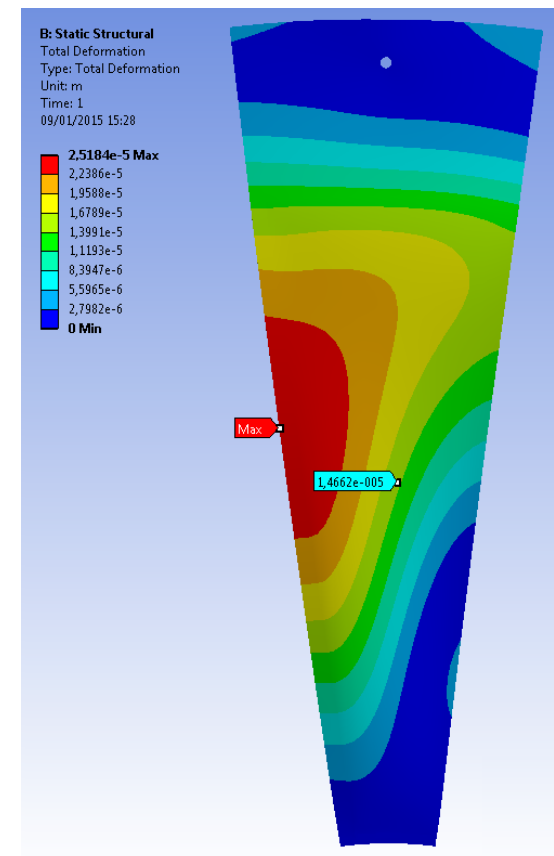
thermo-mechanical

CF support disk for ILD-FTD1 in production in INTA, Madrid

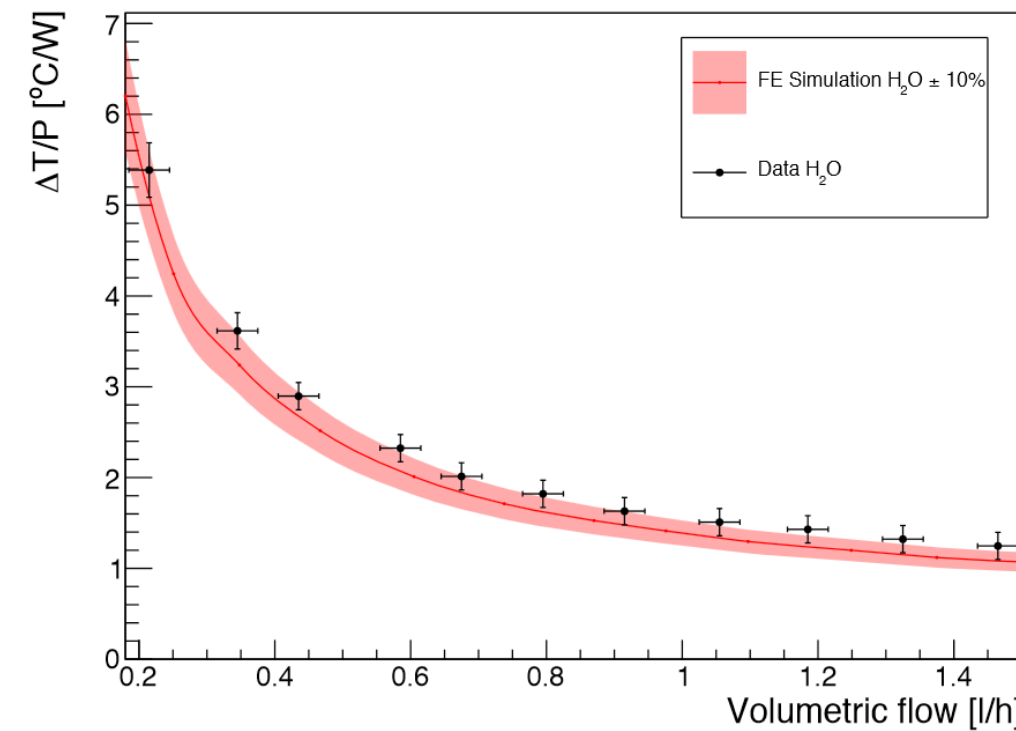
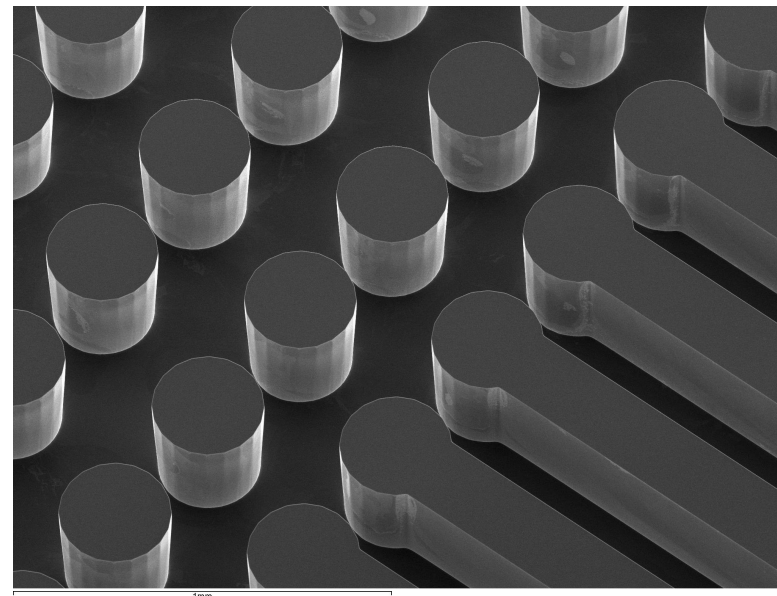
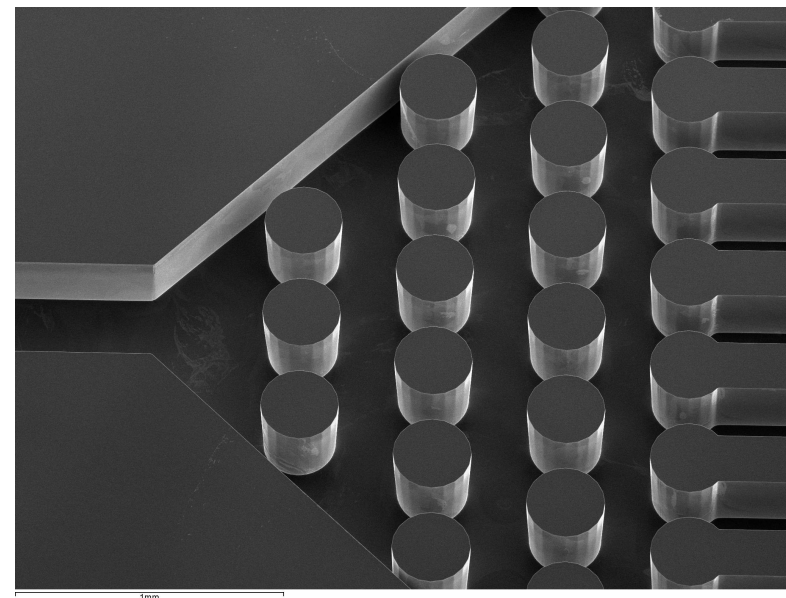
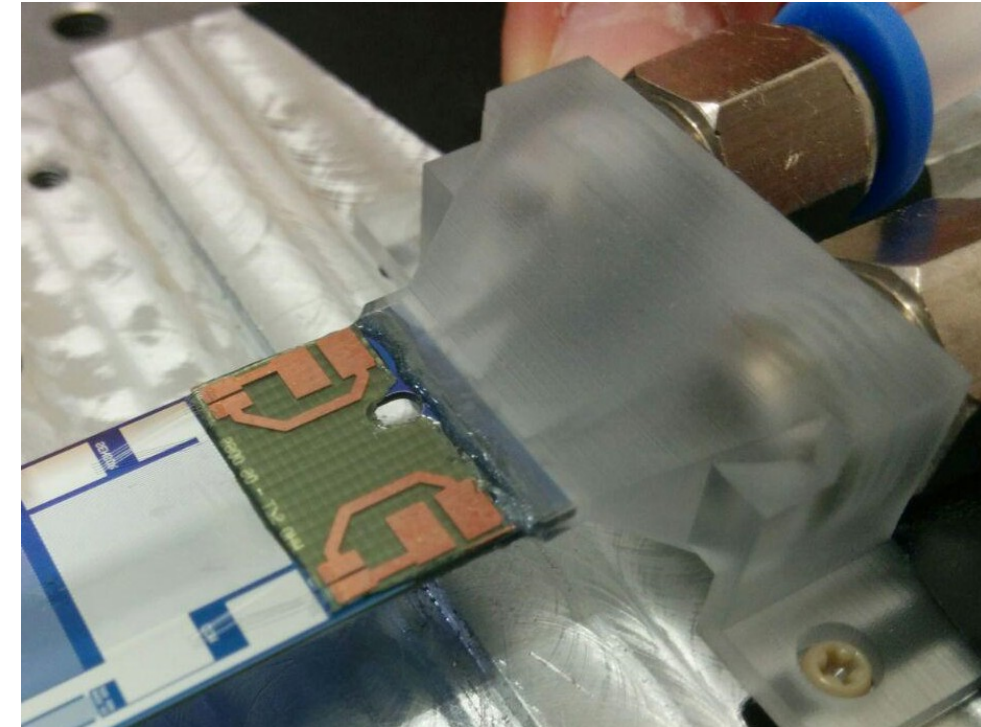
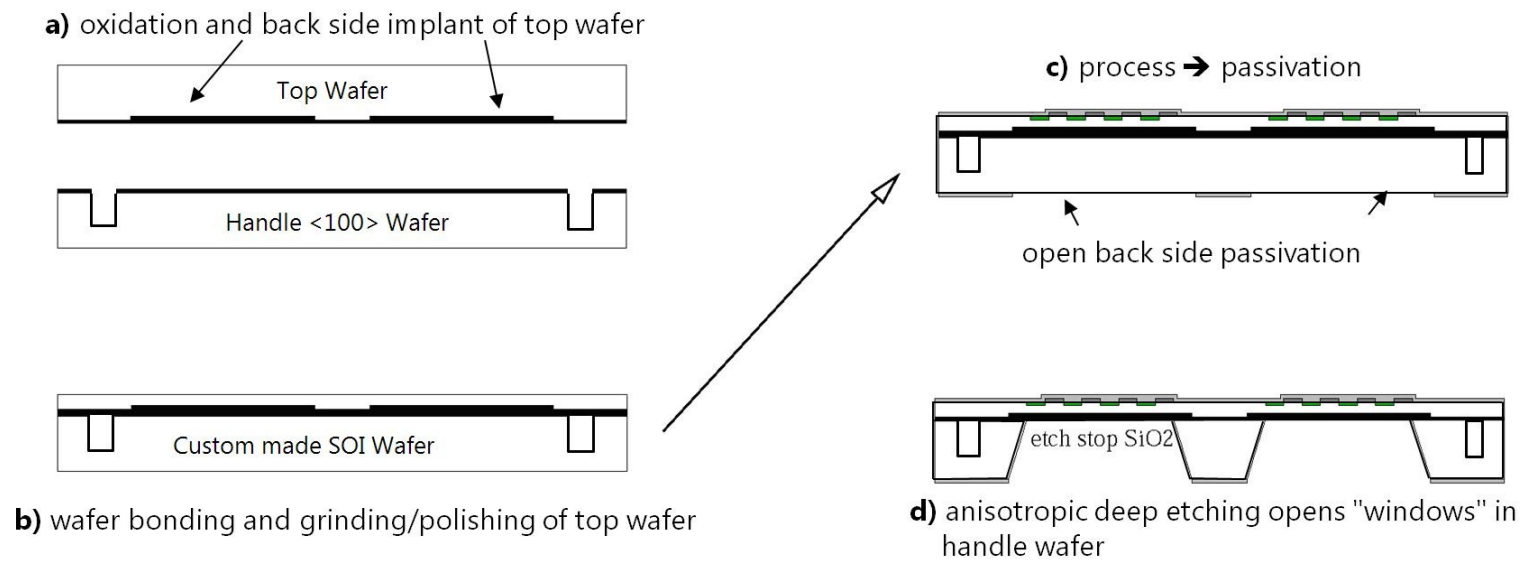


Laci Andricek, HLL Munich

Mechanical samples for all-silicon petals. Most of the area is thinned to 75 μm , resistor circuits emulate power consumption of sensor and ASICs following DEPFET pattern.

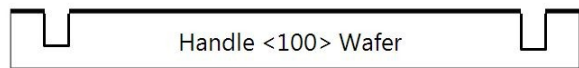


Integrated cooling!



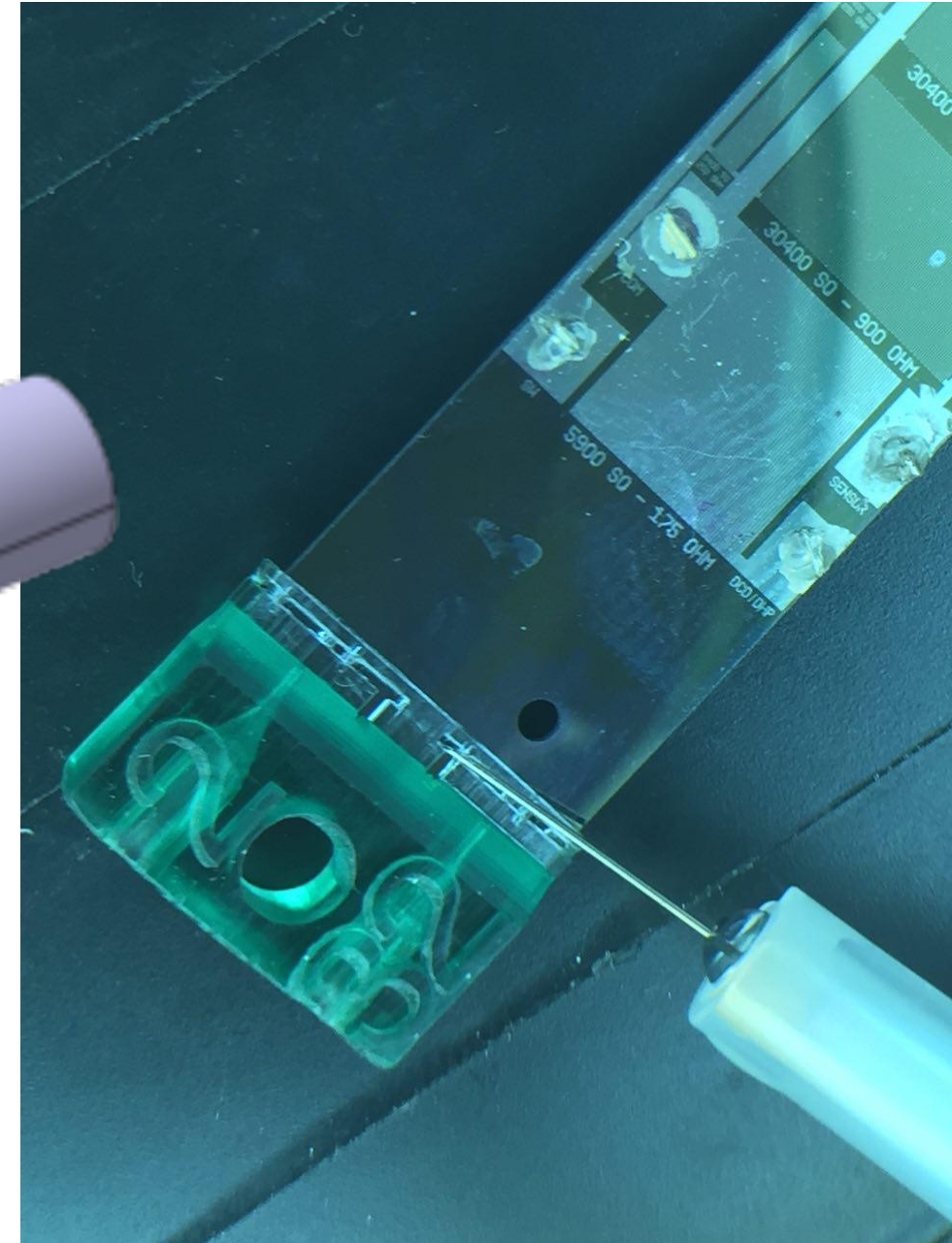
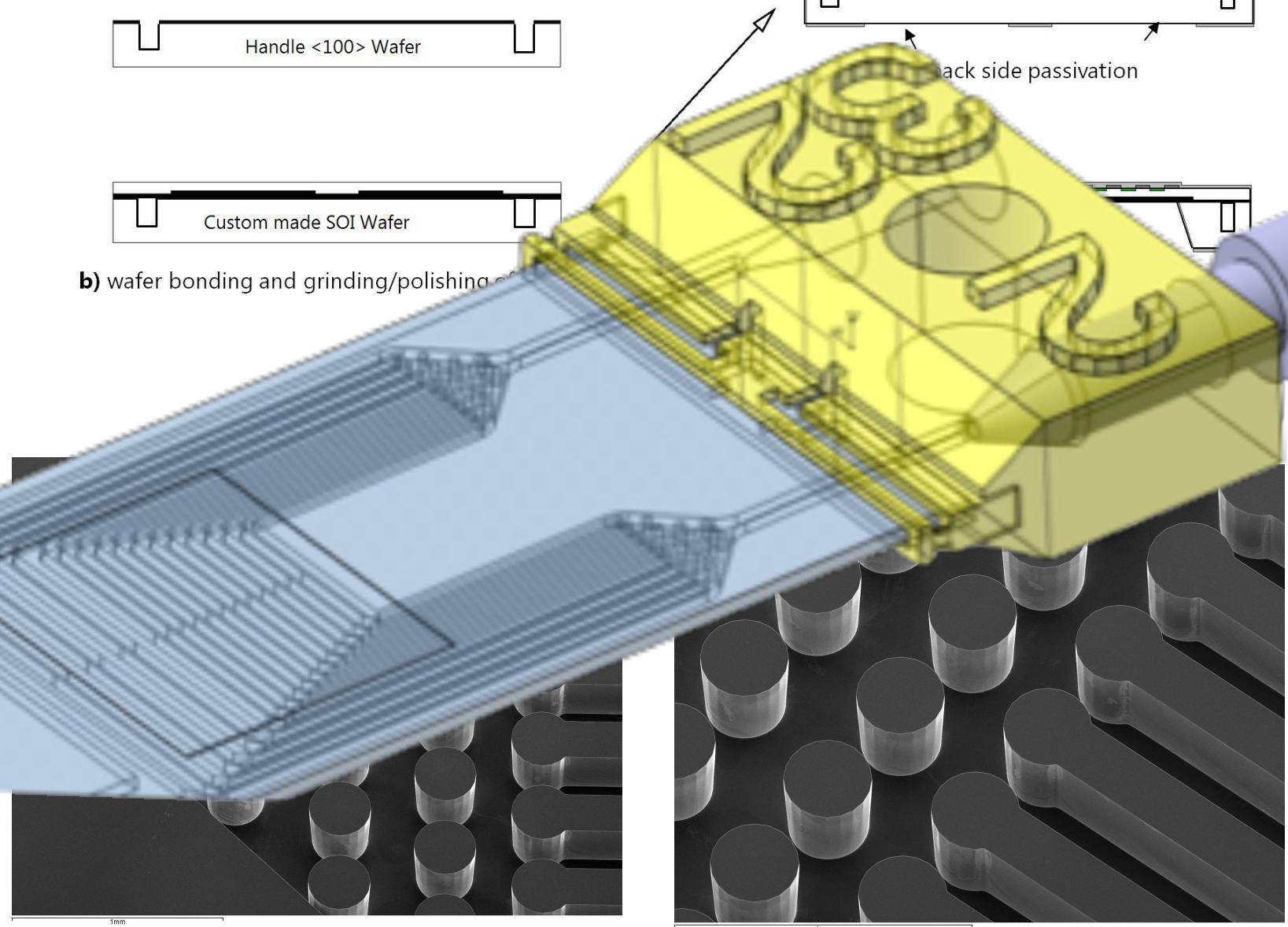
Integrated cooling!

a) oxidation and back side implant of top wafer



b) wafer bonding and grinding/polishing

c) process → passivation



Avalanche Detectors with Low Internal Gain

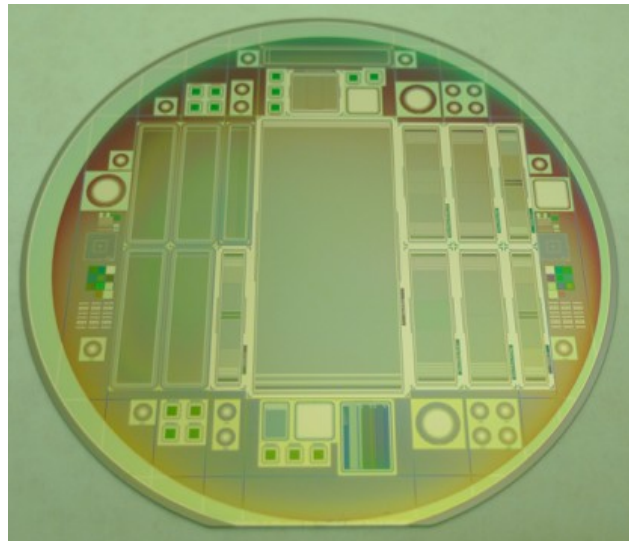
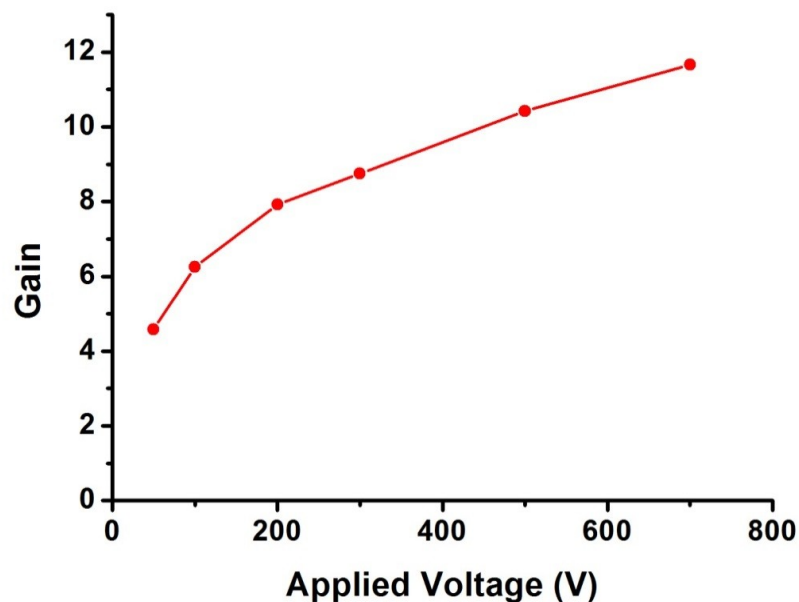
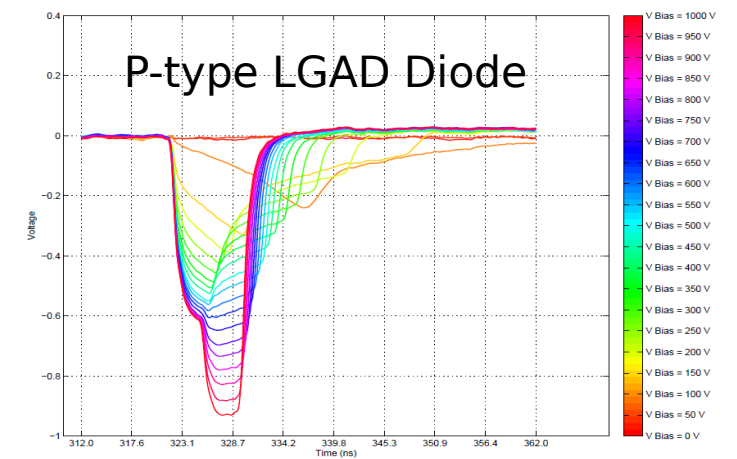
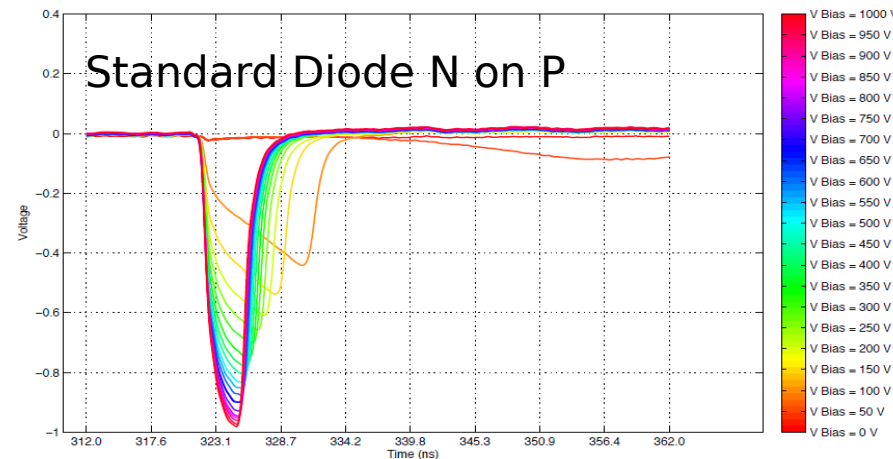
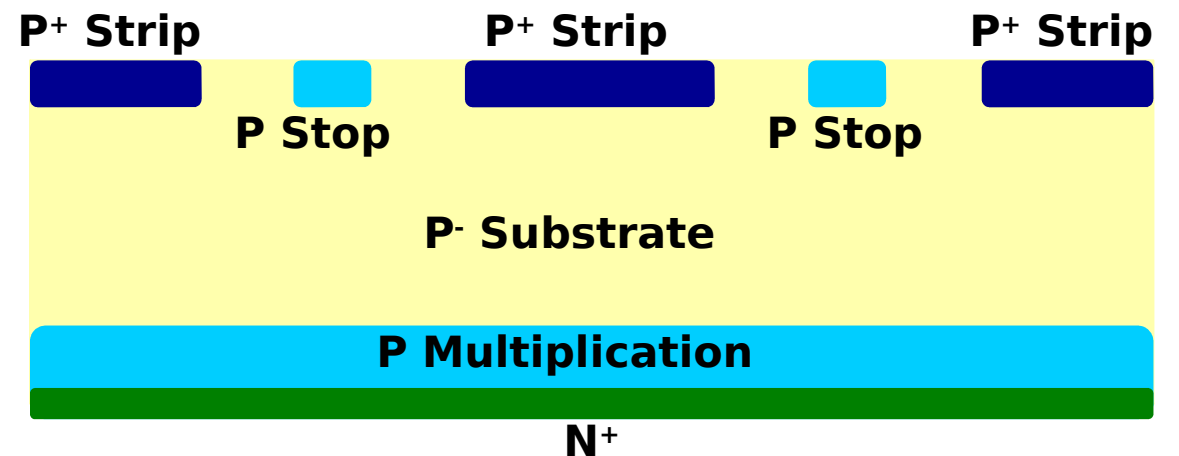


Figure 1. General view of a wafer with the new **resistive microstrip** detectors fabricated at IMB-CNM clean room

Use CNM in-house processes: capability for thin 6" wafers, full custom implants and segmentation (pixel/strips)



Signal multiplication in the sensor
→ higher S/N or thinner silicon sensor



Next step: segmented LGAD detector (iLGAD)

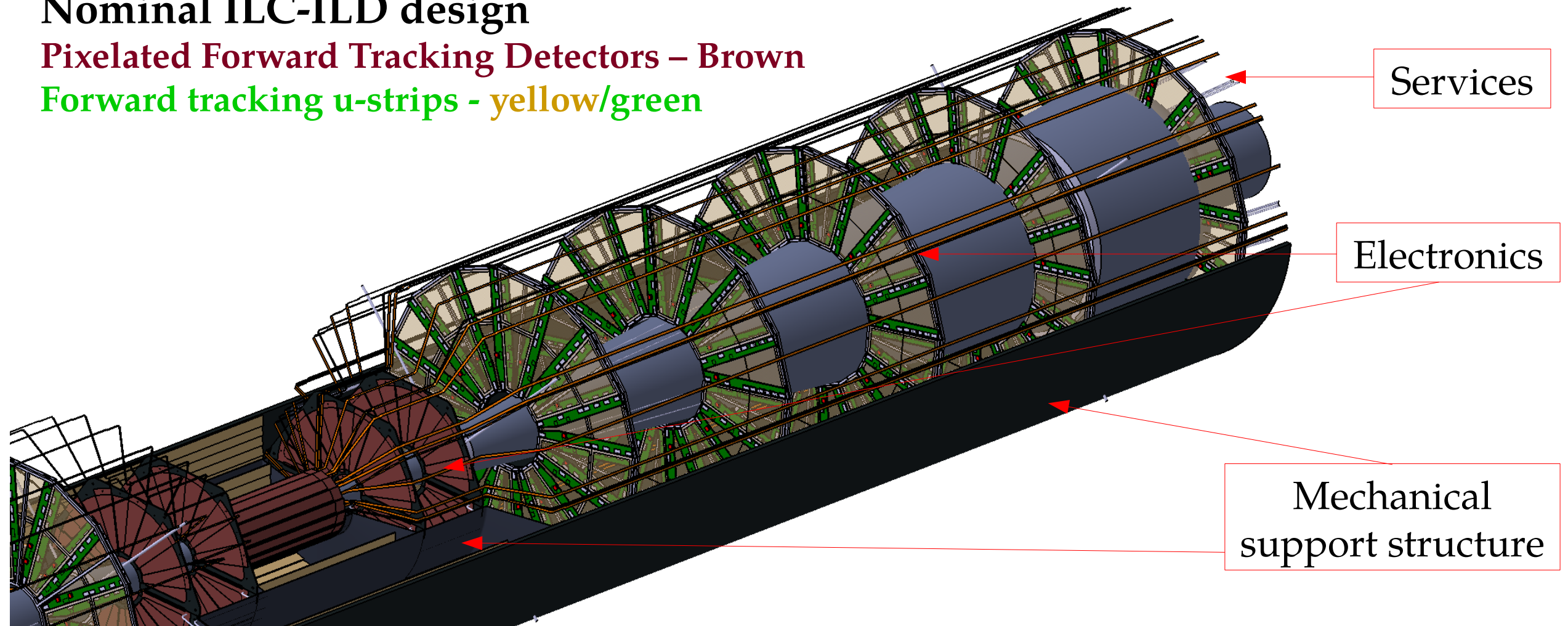


ILD-FTD design

Nominal ILC-ILD design

Pixelated Forward Tracking Detectors – Brown

Forward tracking u-strips - yellow/green



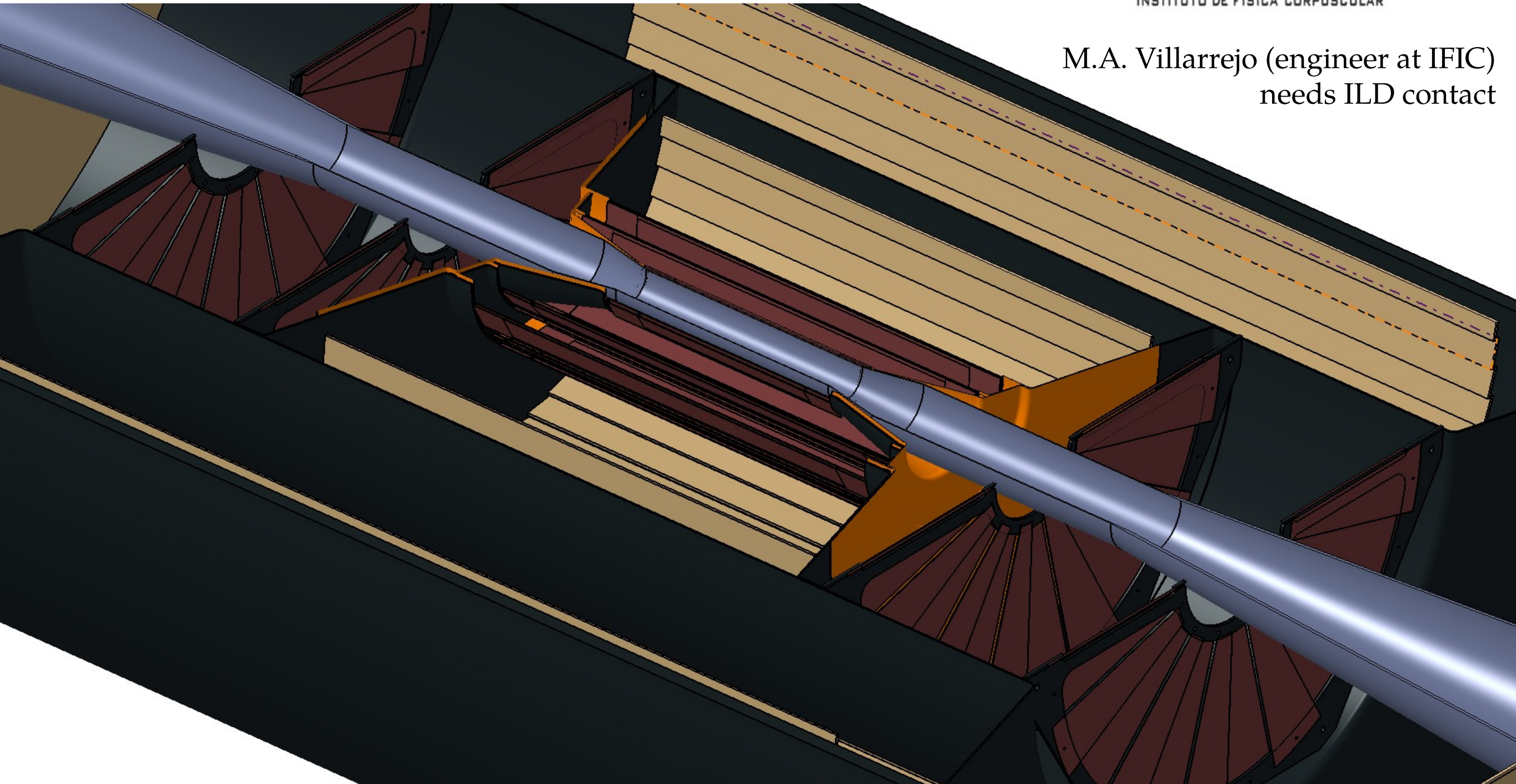
FTD: detailed design

A detailed design for innermost Forward Tracking Disks (and VXD)

- end-of-ladder material (technology-specific)
- cables & services (generic, inner-tracker level problem)

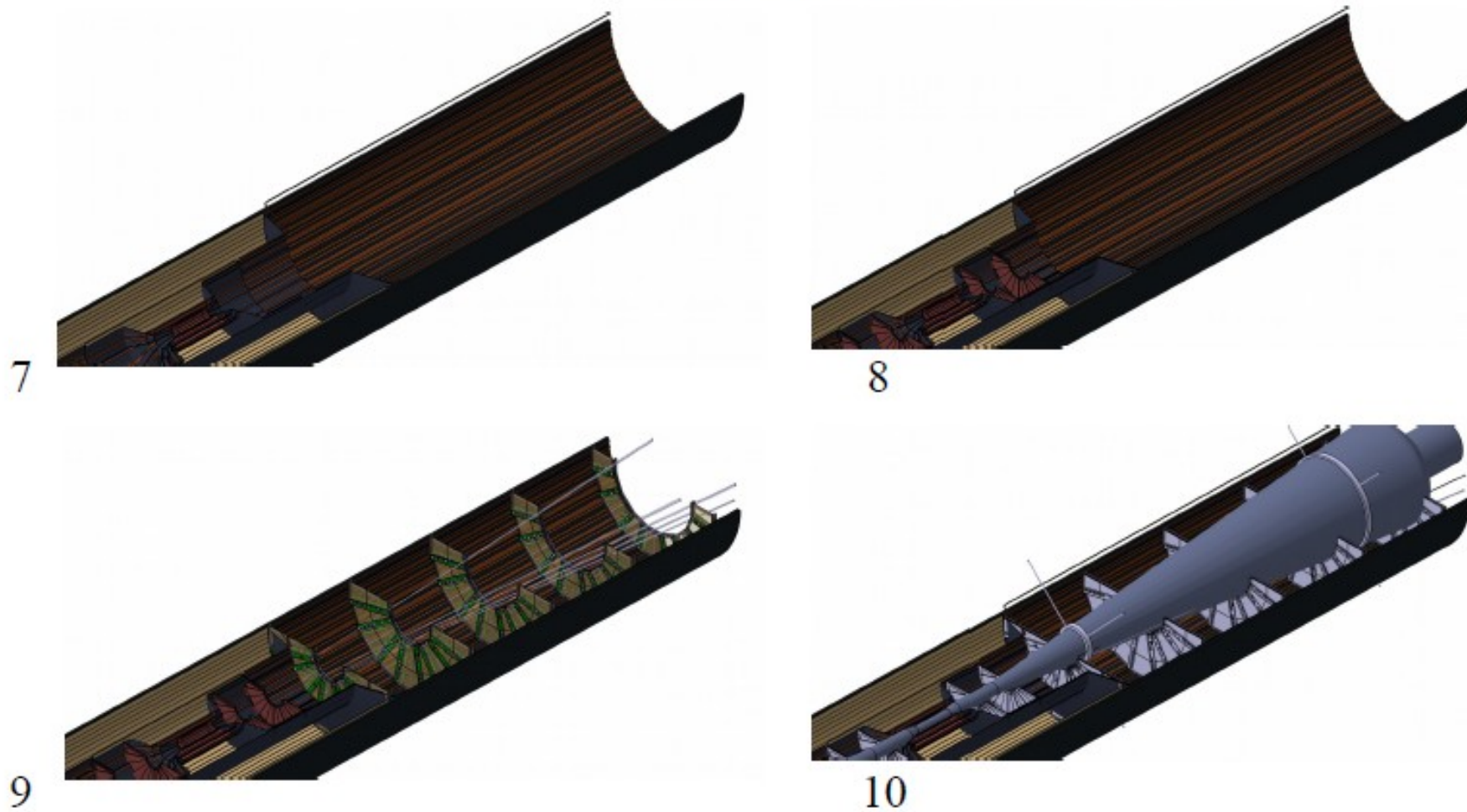


M.A. Villarrejo (engineer at IFIC)
needs ILD contact



Assembly procedure

Assembly strategy



Steps:

6 → 7 VXBD 1-2 &
CFRP

7 → 8 FTD 1-2 &
CFRP

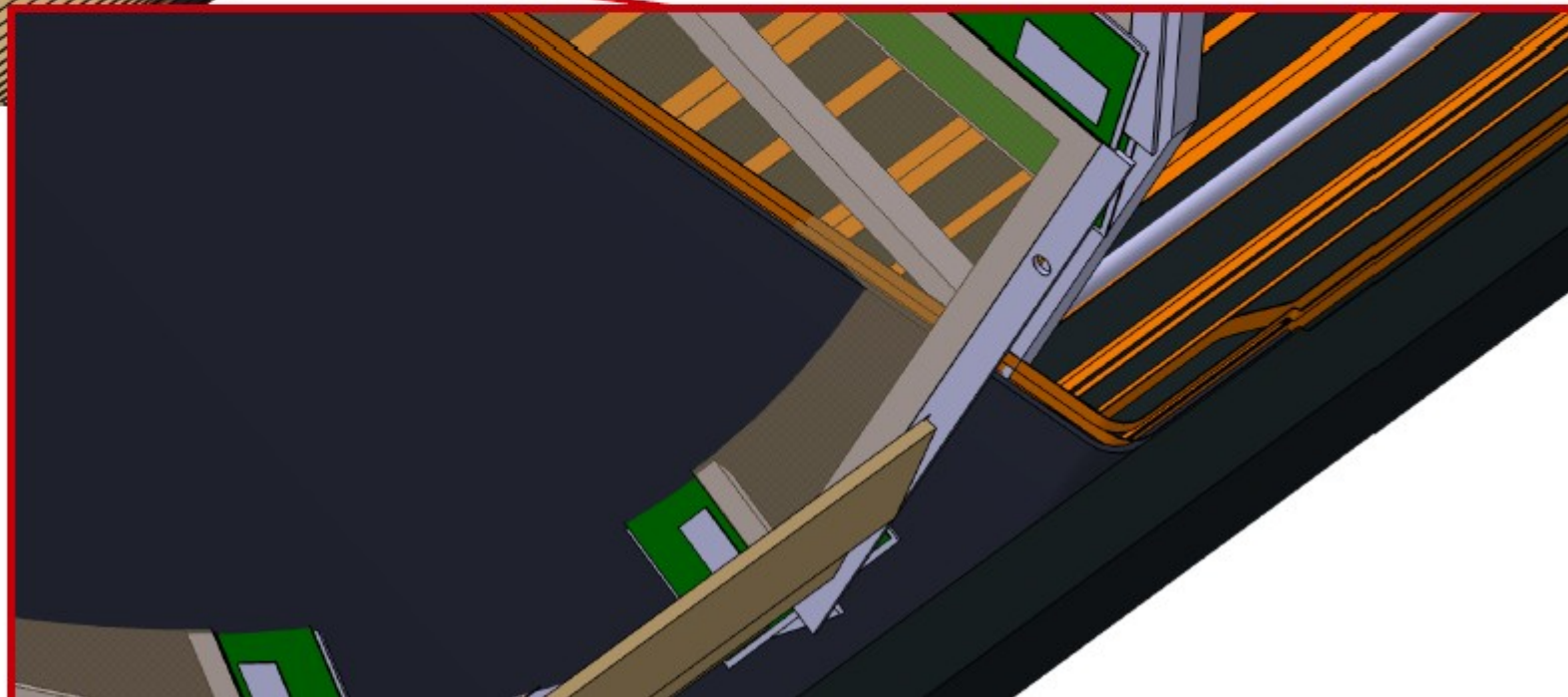
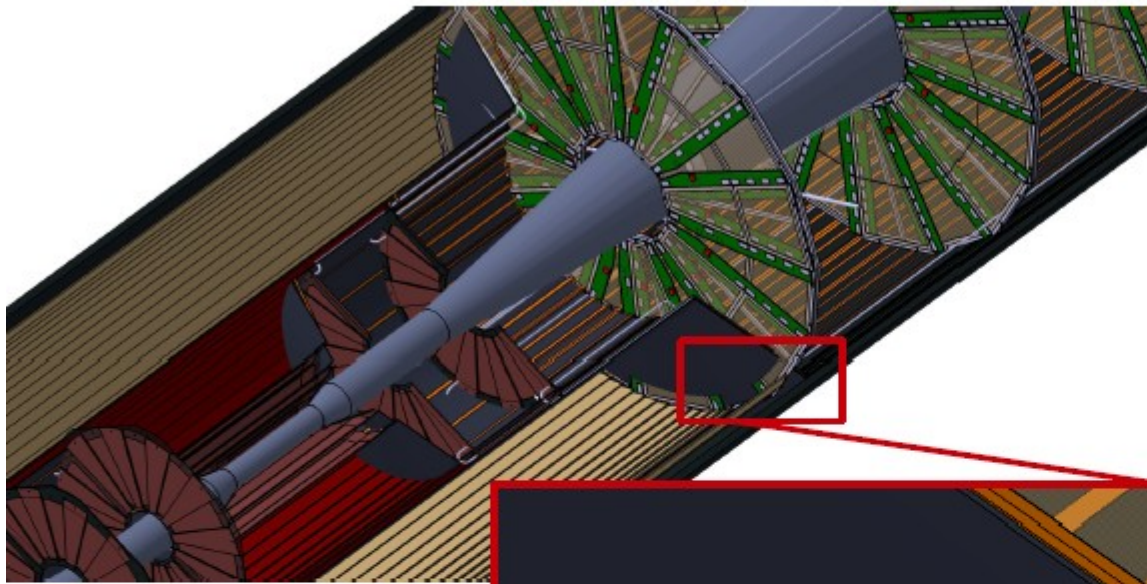
8 → 9 FTD 3-7 &
CFRP (x2)

9 → 10 Beam Pipe



Envelopes

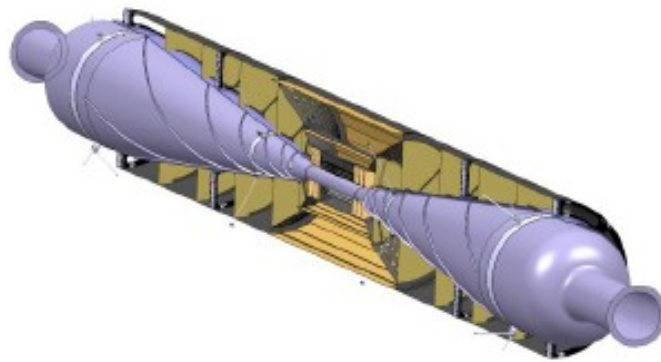
Some inconsistencies in TDR
Unclear envelopes of SIT and FTD
→ little progress since integration workshop,
Address in Santander



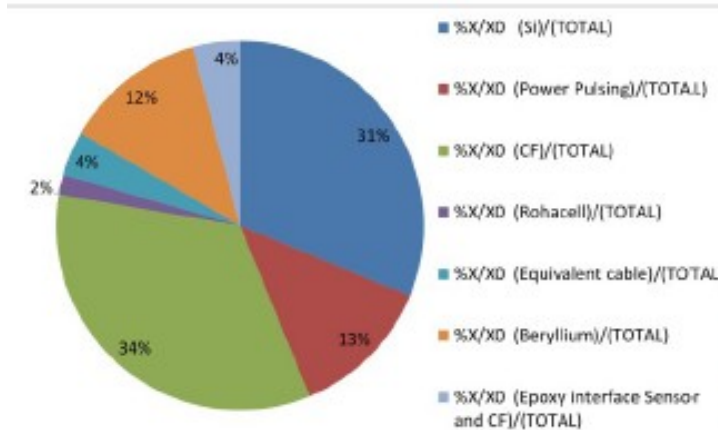
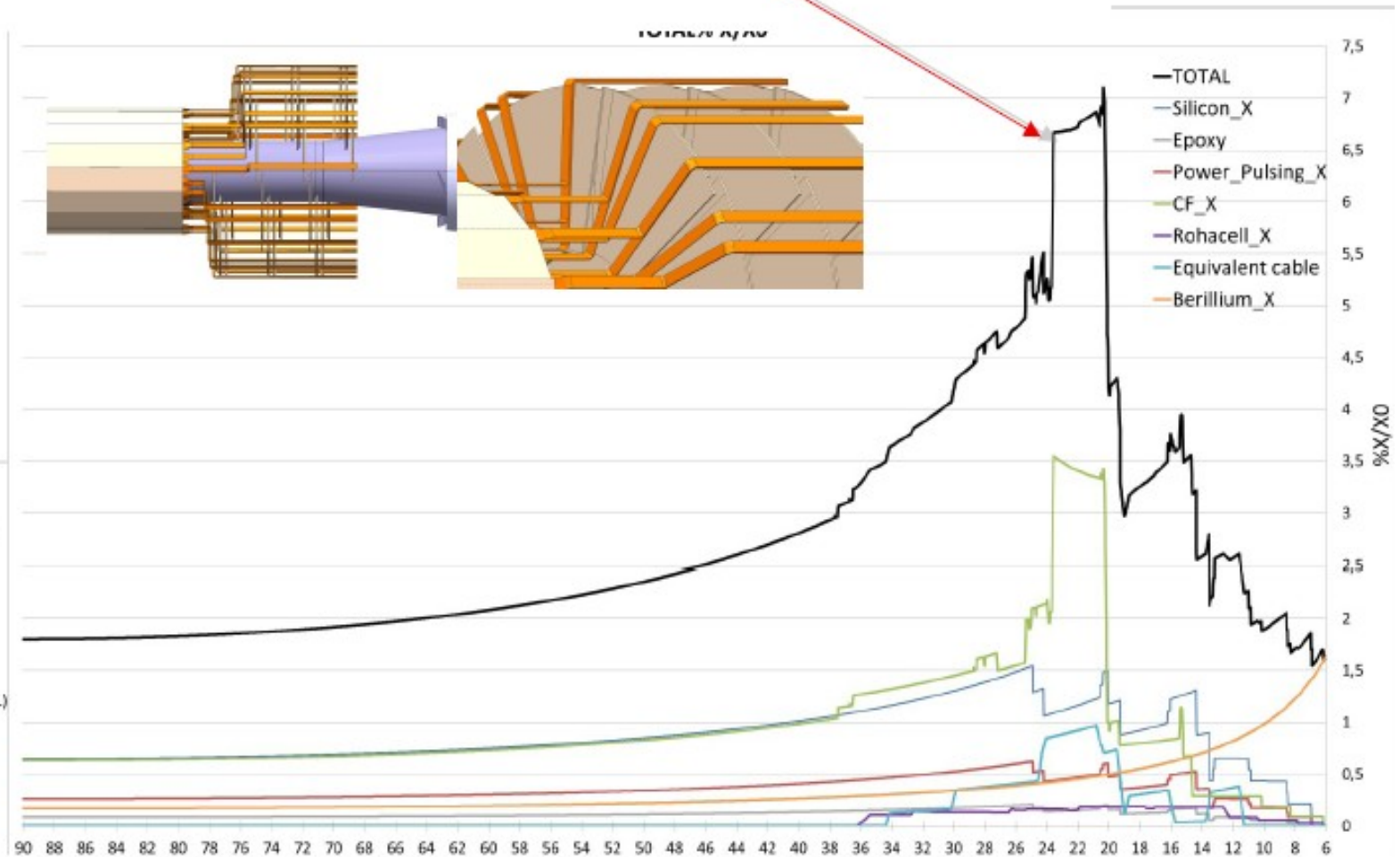
Engineered design

→ feed back into simulation for increased realism

TOTAL



Services and cables outside the FTDs

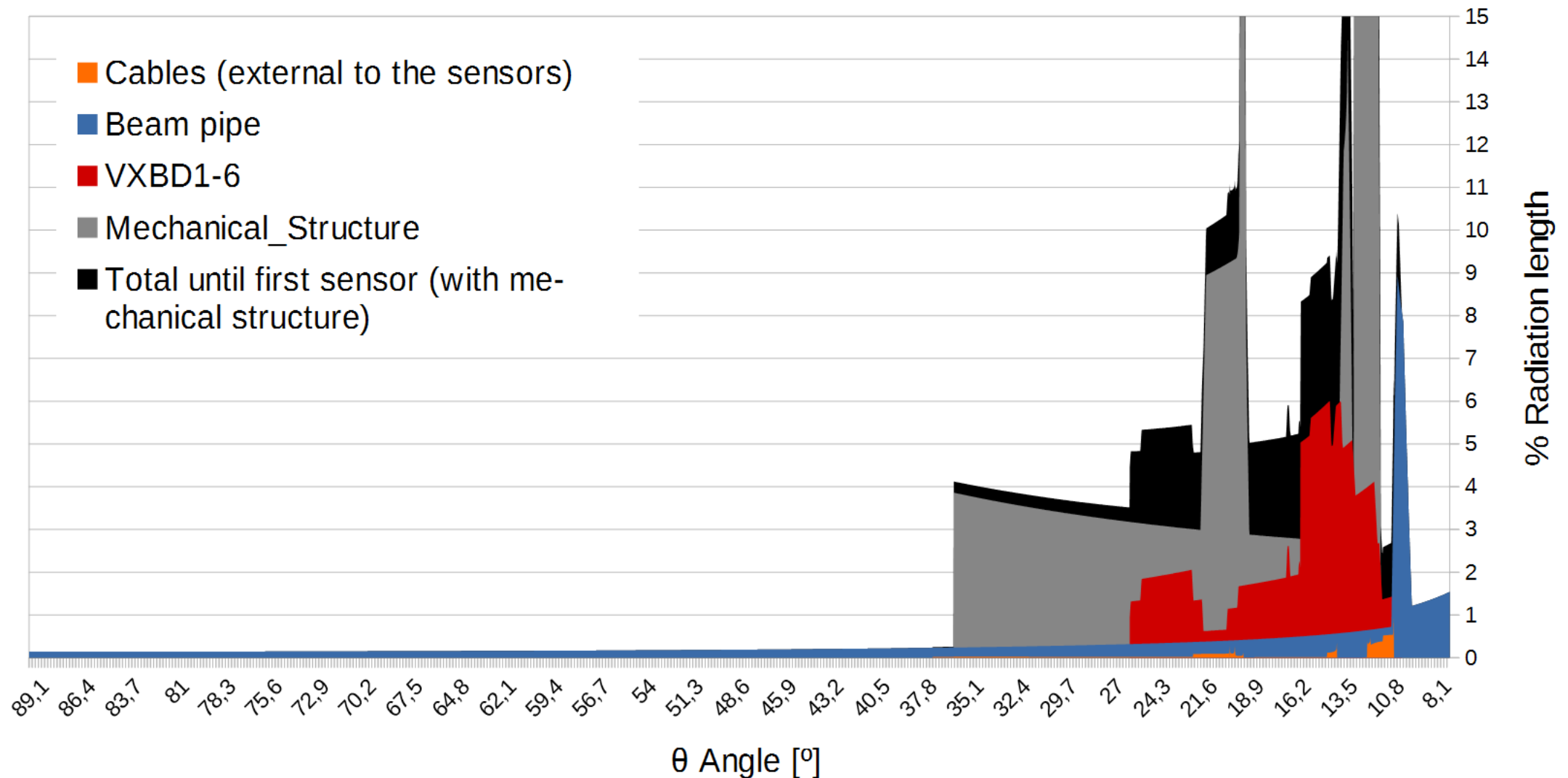


Impact on physics



Minimize the impact on physics of service material
Vertexing at low angle with FTD requires no material in front of silicon, but VTX barrel services must go out...
Requires inner-detector-wide solutions!

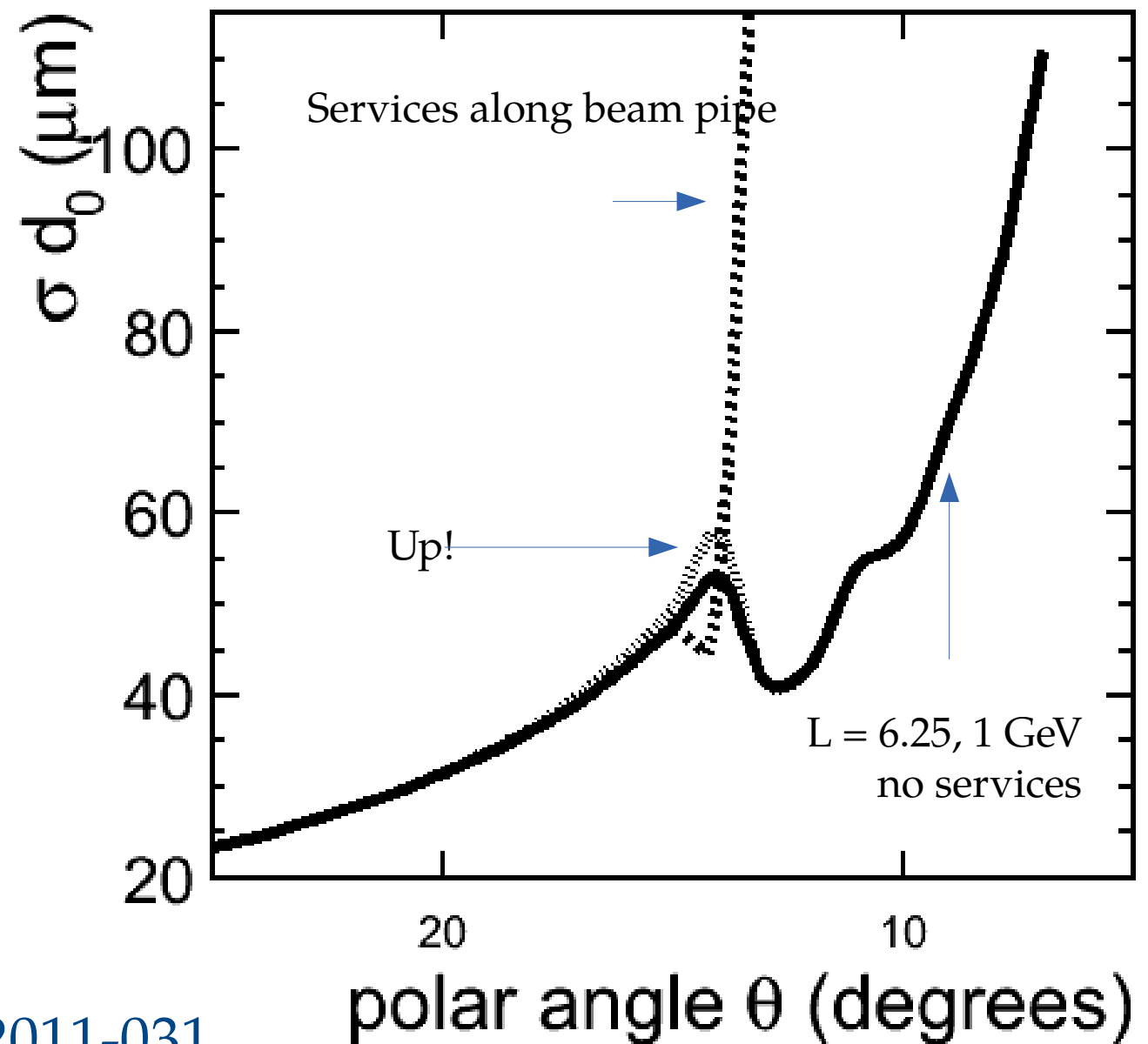
Radiation length contribution of the elements before the first sensitive layer



A decision that needs to be taken...

The forward region clearly does NOT like the services routed along the beam pipe

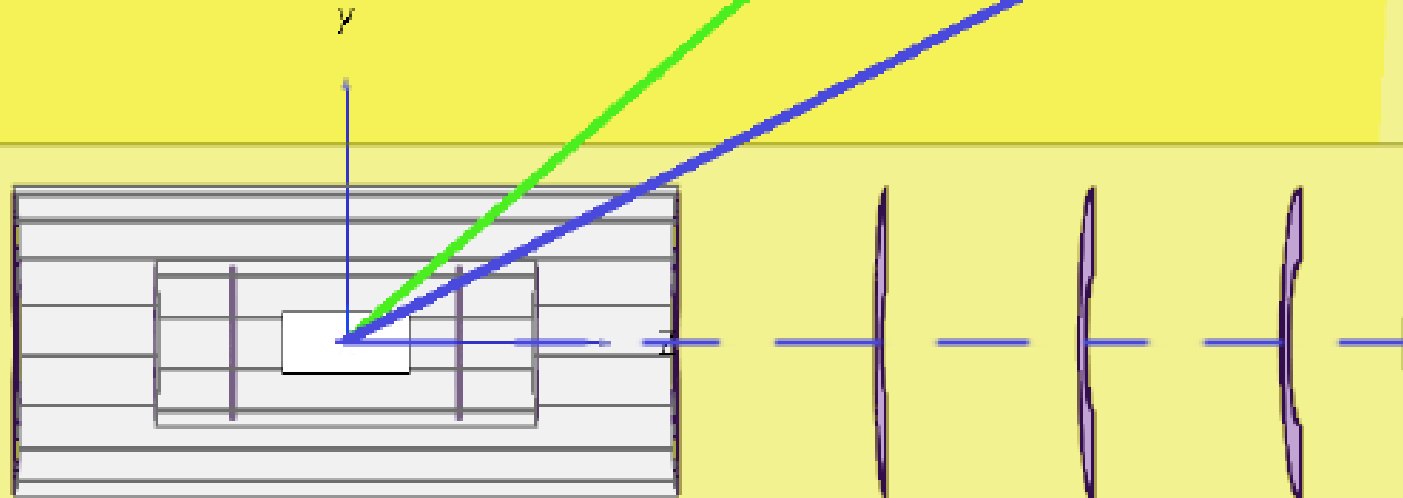
If anything close to a radiation length comes in the way between endcap and interaction point we can forget about forward vertexing



See also CLIC study LCD note 2011-031

Forward Pattern Recognition is a problem

Complicated region in detector cause an additional peaks in nonreconstructed tracks plots



Reconstruction of low-momentum forward tracks has never worked well in ILD

Too few layers, too much space in between....

Algorithms have improved, but problem seems to remain

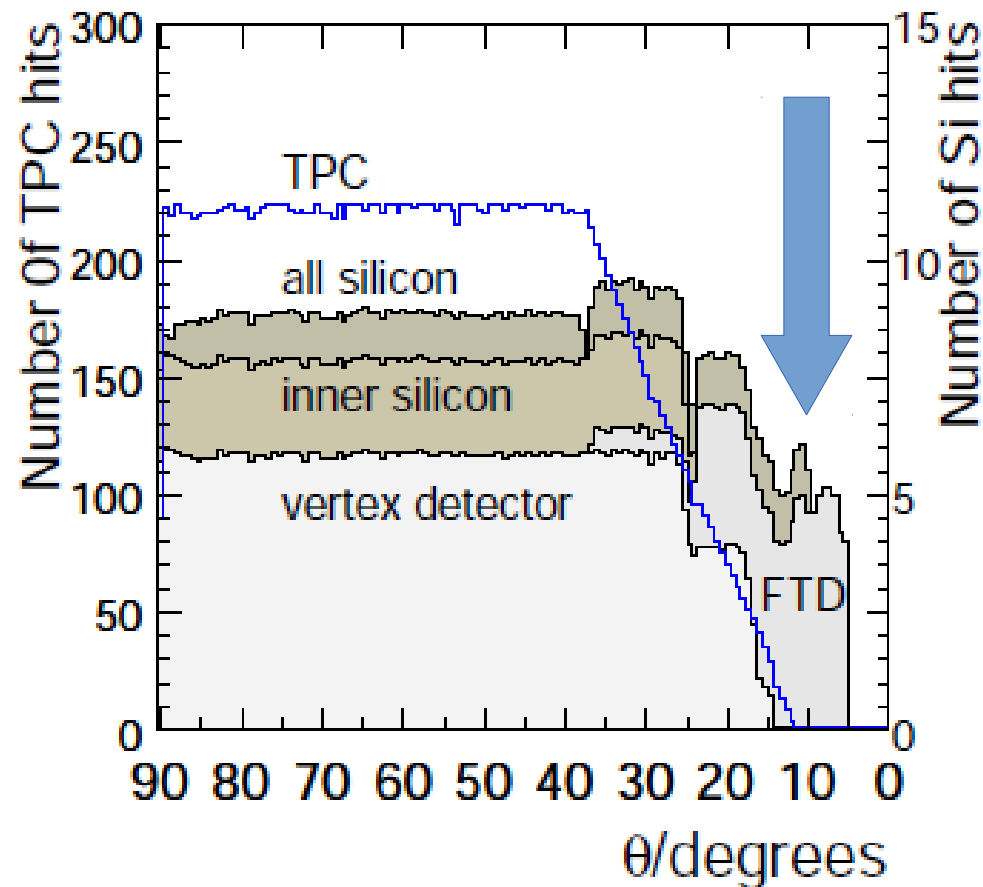
Need good efficiency AND low fake rate!

This affects physics analyses!

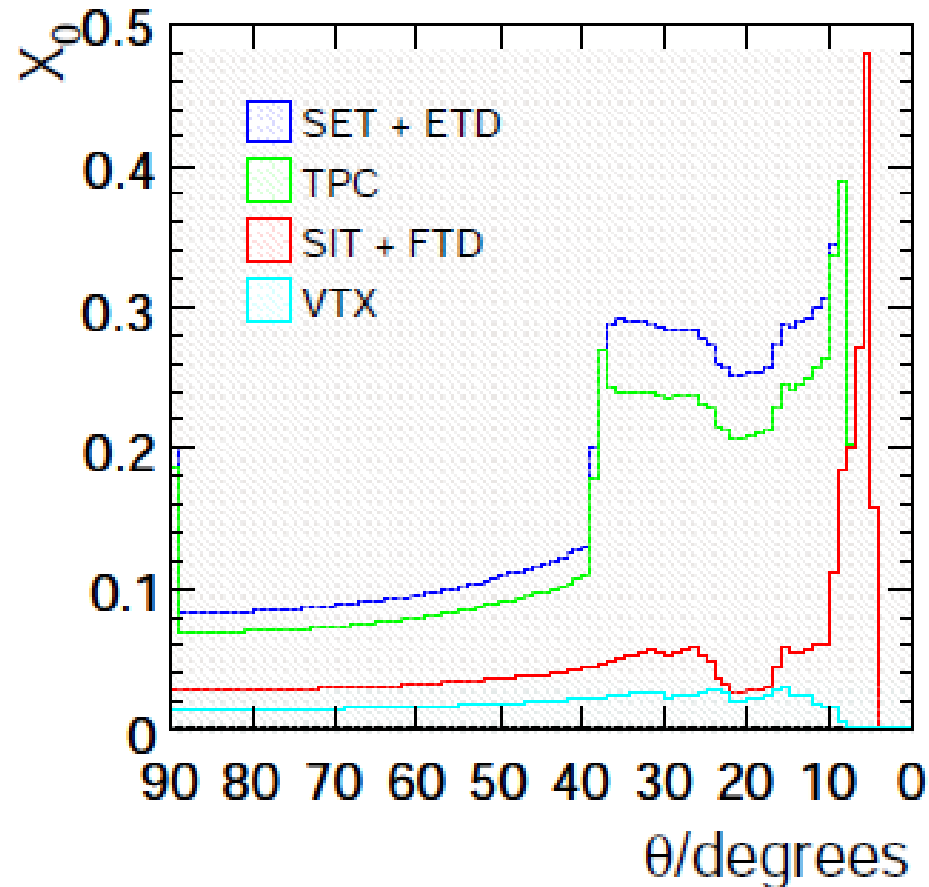
V. Bilokin, TopLC15



Forward tracking



Number of hits in the different subsystems of the ILD detector



Radiation length

ILD DBD.
arXiv:1006.3396

The forward tracker has to cover a dense region, with very few measurements. **Do we need to reinforce the FTD?**

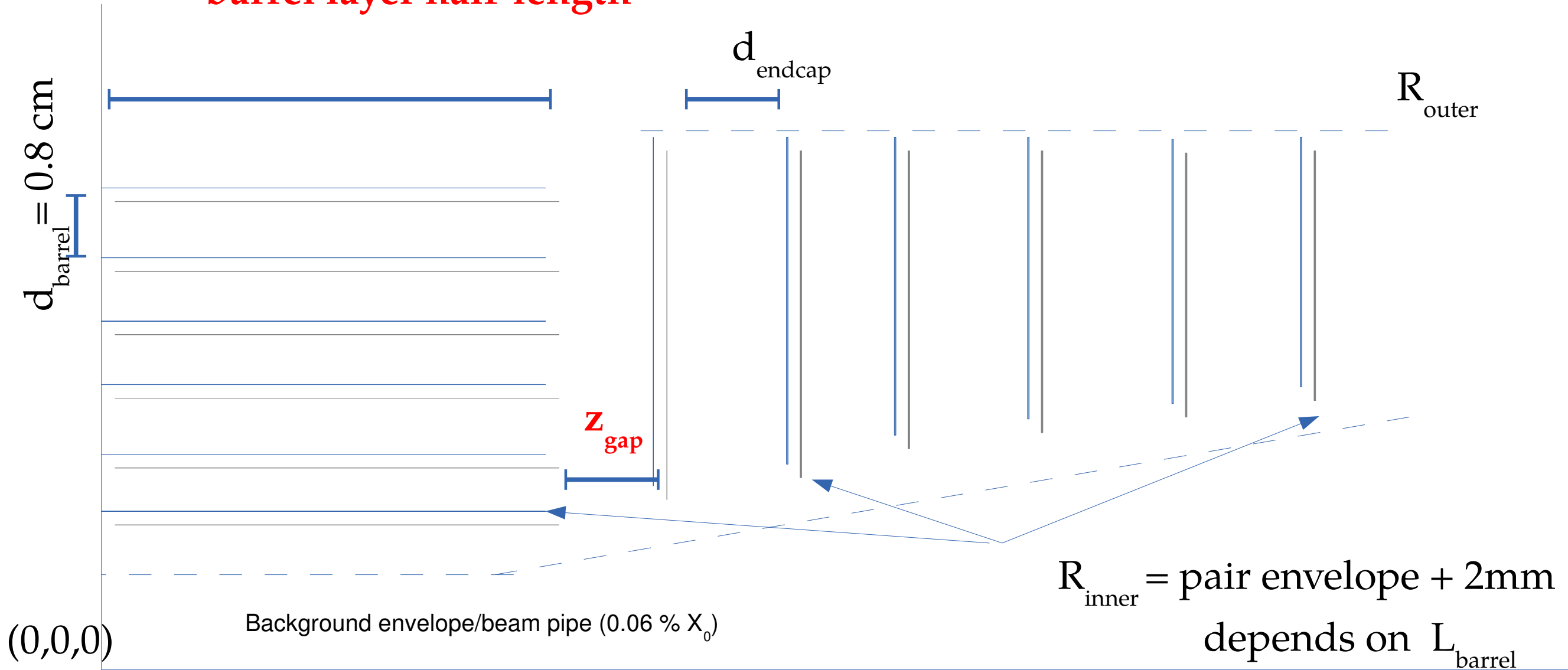
SiD has complete VXD end-cap and also CLIC opted for this design,
M. Vos, D. Dannheim et al, arXiv:1203.0942

Slide from AWLC14



A simplified view

barrel layer half-length

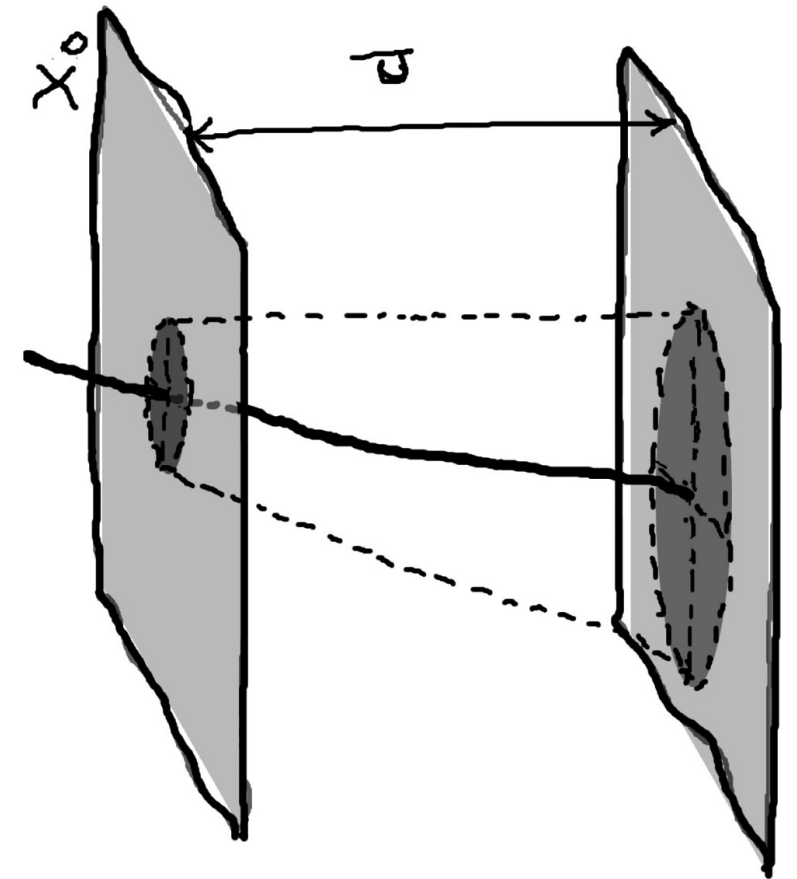


ILC-SiD: $L_{\text{barrel}} \sim 6.25 \text{ cm}$, $z_{\text{gap}} \sim 1 \text{ cm}$, $d \sim 2 \text{ cm}$

ILC-ILD: $L_{\text{barrel}} \sim 12.5 \text{ cm}$, $z_{\text{gap}} \sim 10 \text{ cm}$, $d > 10 \text{ cm}$

CLIC-iLD: $L_{\text{barrel}} \sim 12.5 \text{ cm}$, $z_{\text{gap}} = 2 \text{ cm}$, $d \sim 3 \text{ cm}$

A concrete proposal



Alternative geometry to be tested for tracking (especially pattern recognition) performance:

- | A real compact VXD end-cap, with five closely spaced disks, instead of two large pixelated disks far away
- | Reduced gap between barrel and first FTD disks (include disks in cryostat if needed)



Summary

R&D programme progressing steadily

- measurements on thermo-mechanical performance of ultra-transparent detectors
- complete mechanical solution + integrated cooling
- micro-strip detectors with internal gain

FTD design

- engineering design for services exists
- important design choices pending since a few years
- reinforce FTD pixels for pattern recognition for low momentum forward tracks

